

# SOT800A

flanged double-ended ceramic package; 2 mounting holes; 4 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	CDFM4
<b>Package type industry code</b>	SOT800A
<b>Package style descriptive code</b>	CDFM (ceramic double-ended flange mount)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	C (ceramic)
<b>Mounting method type</b>	F (flange mount)
<b>Issue date</b>	18-11-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	31.7	-	32	32.3	mm
E	package width	14.4	-	14.5	14.6	mm
A	seated height	6.6	-	6.9	7.1	mm
n <sub>2</sub>	actual quantity of termination	-	-	4	-	



## 2. Package outline

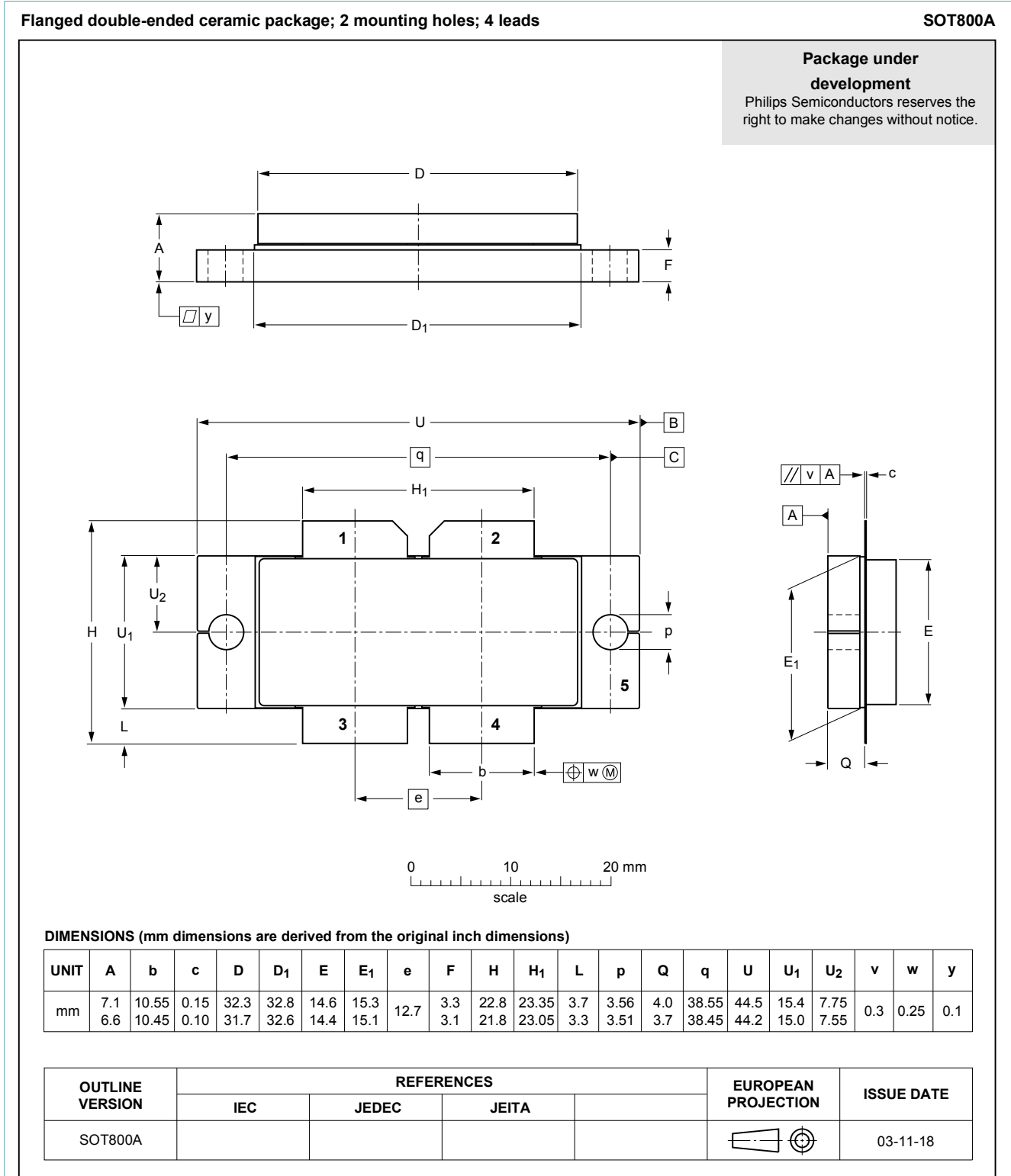


Fig. 1. Package outline SOT800A

### 3. Legal information

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